

37th International Electronics Manufacturing Technology/18th Electronics Materials & Packaging Conference (IEMT-EMAP 2016)



G Hotel, Penang, Malaysia. $20^{th} - 22^{nd}$ September, 2016

CONFERENCE	DECICTD	TION EODM	

A. Participa	nt's Information (u	se additional sheet if needed).					
Nam	<u>ne</u>	<u>Designation</u>	Preferred Name on Badge	IEEE Membership No.			
1							
2							
B. Contact I	nformation						
Organization:		Dent ·	Tel :	Fax ·			
City/State : _		•	•				
DADTI. CON	IEEDENICE DECI	REGISTRATION		di el)			
PARTI: CON	FERENCE REGIS	STRATION (Please tick (7) on	the appropriate box/boxes acco	ordingly).			
CON	FERENCE ON 21 ST & 22	2 ND SEPTEMBER 2016 (2 FULL DAYS).	EARLY BIRD REGISTRATION FEE (BI	EFORE 15 TH AUGUST 2016)			
CATEGORIES		CONFERENCE FEE	SHORT COURSE FEE	CONFERENCE + SHORT COURSE			
SPEAKERS		[] RM650	[] RM600	[] RM1200			
[] IEEE MEMI	BER	[] RM750	[] RM600	[] RM1250			
NON IEEE I		[] RM850	[] RM700	[] RM1500			
	ESTUDENTS	[] RM600	[] RM500	[] RM1000			
			ns that are submitted after 15 th August 2016	T			
Note: 1 Ringgit (N	MYR) is approximately US	S\$0.23. All fees are inclusive of 6% GST.	TOTAL AMOUNT				
	ORT COURSE RE	SHORT COURSE ON 20 ST SEP		gly) COURSE (1:30 – 5:30 PM)			
	rse I (Full Day)		111 11111111111111111111111111111111111	Control (Control Control Contr			
Topic : Instructor :	Chip-to-Package Interconnect Technology: Fundamentals and Future Trend						
	rse II (Full Day)						
Topic : Instructor :	Fanout Wafer Level Packaging (FO-WLP) – Innovative and Novel Solutions of Advanced Packaging Dr. Yoon Seung Wook STATSChipPAC-JCET, SINGAPORE						
	rrse III (Full Day)						
Topic : Instructor :	Copper Ball Bonding Materials, Intermetallic & Reliability Dr. Christopher Breach ProMat Consultants, SINGAPORE						
	ırse IV-A (Half Day)		[] Short Course IV-B (Half Da	• /			
Topic :		Development – Upcoming Cerning Reliability and	Topic: Achieving High Joints	Reliability for Lead-Free Solder			
	Applications		Instructor: Dr. Ning Cheng	Lee			
Instructor:	Dr. Klaus Mueller	GERMANIA	Indium Corporat	ion, USA			
	Infineon Technologi	ies, GERMAN Y					
		PAYMENT DETAILS (IN					
			n form, and send along with check or Ringgit Malaysia to: IEEE CPMT M	bank draft payment. Please do not mai IALAYSIA.			
[] Cheque/B	ank Draft		Cheque/Bank Draft No: Bank Name:(Only cheque or bank draft drawn in Malaysian bank are acceptable)				
[] Credit Ca	rd Payment	Please pay online.					
IEMT-EMAP 2		tention : Hafiza Hamid) ound Floor, No. 10, Persiaran Bu	kit Jambul,				

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Email: <u>iemt-emap2016@crest.my</u> Conference website: <u>http://ewh.ieee.org/r10/malaysia/cpmt/Home/iemt/2016/iemt2016.html</u>